Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 8			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	- I _D = - 250 μA		7.15		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 1.66		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 0.45		- 1.0	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = -8 V			- 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 8 V, V _{GS} = 0 V			- 1	μА
		V _{DS} = -8 V, V _{GS} = 0 V, T _J = 55 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 1.8			Α
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 0.58 A		0.450	0.542	Ω
		V _{GS} = - 2.5 V, I _D = - 0.47 A		0.655	0.798	
		V _{GS} = - 1.8 V, I _D = - 0.2 A		0.950	1.2	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 4 V, I _D = - 0.58 A		1.2		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = - 4 V, V _{GS} = 0 V, f = 1 MHz		62		pF
Output Capacitance	C _{oss}			30		
Reverse Transfer Capacitance	C _{rss}			12		
Total Gate Charge	Q _g	V _{DS} = - 4 V, V _{GS} = - 4.5 V, I _D = - 0.58 A		1.0	1.5	nC
Gate-Source Charge	Q _{gs}			0.19		
Gate-Drain Charge	Q _{gd}			0.20		
Gate Resistance	R_{g}	f = 1 MHz		6.3		Ω
Turn-On Delay Time	t _{d(on)}	V_{DD} = - 4 V, R_L = 8.7 Ω $I_D \cong$ - 0.46 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		9	14	ns
Rise Time	t _r			40	60	
Turn-Off Delay Time	t _{d(off)}			50	75	
Fall Time	t _f			60	90	
Drain-Source Body Diode Characterist	ics					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 0.30	- A
Pulse Diode Forward Current	I _{SM}				- 1.8	
Body Diode Voltage	V _{SD}	I _S = - 1.4 A, V _{GS} = 0 V		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = - 1.4 A, dl/dt = 100 A/μs, T _J = 25 °C		25	38	ns
Body Diode Reverse Recovery Charge	Q _{rr}			7	11	nC
Reverse Recovery Fall Time	t _a			9		ns
Reverse Recovery Rise Time	t _b			16		

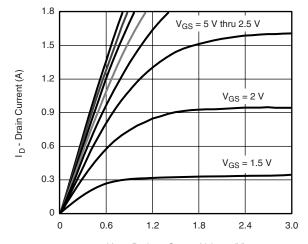
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

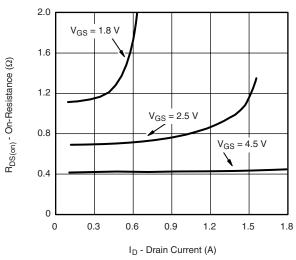


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

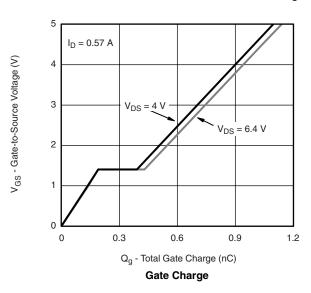


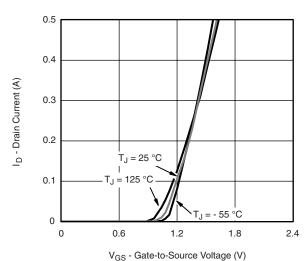
V_{DS} - Drain-to-Source Voltage (V)

Output Characteristics

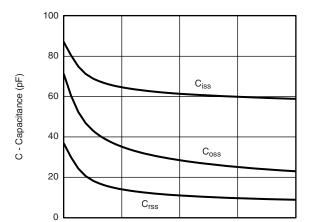


On-Resistance vs. Drain Current and Gate Voltage





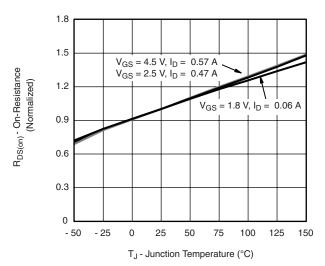
Transfer Characteristics



0

V_{DS} - Drain-to-Source Voltage (V)

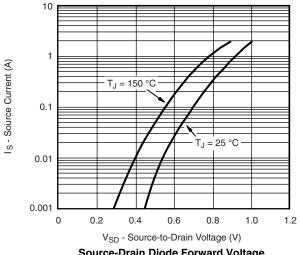
Capacitance

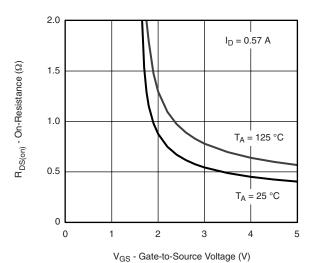


On-Resistance vs. Junction Temperature

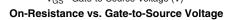
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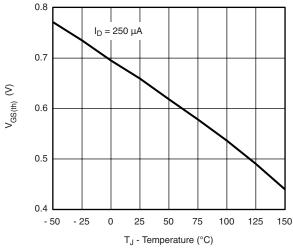
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

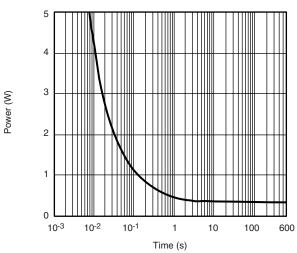




Source-Drain Diode Forward Voltage

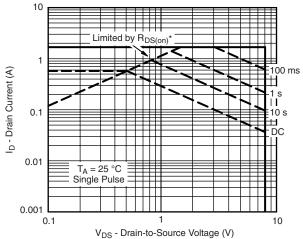






Threshold Voltage

Single Pulse Power, Junction-to-Ambient



* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

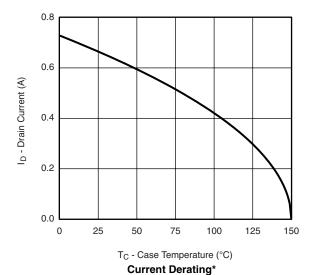
Safe Operating Area, Junction-to-Ambient

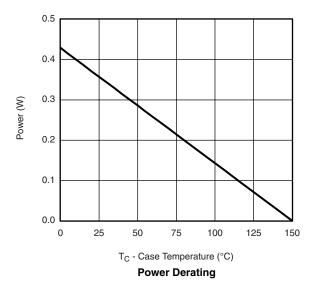






TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





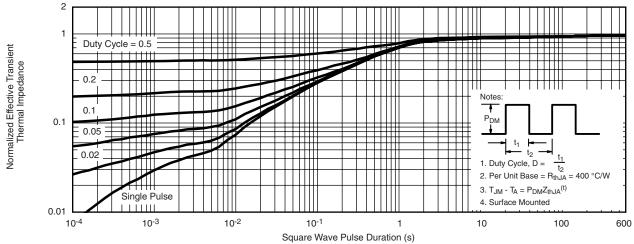
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^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

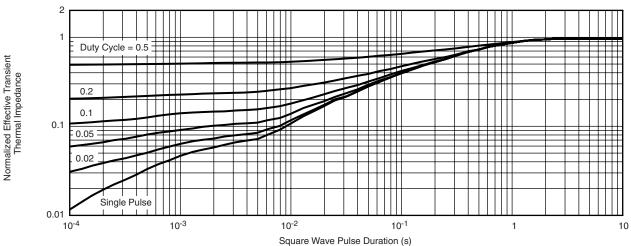
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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